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process of an eighth embodiment of the present invention;

FIGS. 13A to 13C are all a cross-sectional view showing, in sequence, a solid-state image pickup device manufacturing process of a ninth embodiment of the present invention;

FIGS. 14A to 14F are all a cross-sectional view showing, in sequence, a solid-state image pickup device manufacturing process of a tenth embodiment of the present invention;

FIGS. 15A to 15F are all a cross-sectional view showing, in sequence, the solid-state image pickup device manufacturing process of the tenth embodiment of the present invention;

FIGS. 16A and 16B are both a diagram showing a conventional solid-state image pickup device operating in an interlace mode, and specifically, FIG. 16A is a layout plan, and FIG. 16B is a schematic cross-sectional view cut along a line 16B-16B of FIG. 16A; and

FIG. ¹⁷17 is a layout plan showing an exemplary result derived by applying the present invention to a solid-state image pickup device.

DETAILED DESCRIPTION OF THE INVENTION

(First Embodiment)

By referring to FIGS. 1A and 1B, a solid-state image pickup device of a first embodiment is described. Specifically, FIG. 1A is a plan view of layout, and FIG. 1B is the schematic cross-sectional view cut along a line 1B-1B of FIG. 1A.

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